


Features

- Fast Switching Speed
- Low Capacitance
- Low Leakage Current
- Two "BAV70" Circuits in One Package
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**
- **PPAP Capable (Note 4)**

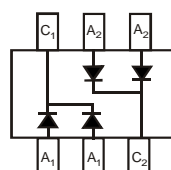
Mechanical Data

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe
(Lead-Free Plating). Solderable per MIL-STD-202, Method 208 
- Orientation: See Diagram
- Weight: 0.006 grams (Approximate)

SOT363



Top View

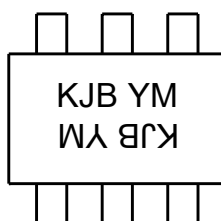

 Top View
 Internal Schematic

Ordering Information (Notes 4 & 5)

Part Number	Qualification	Case	Packaging
BAV70HDWQ-13	Automotive	SOT363	10,000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to http://www.diodes.com/product_compliance_definitions.html.
 5. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



KJB = Product Type Marking Code
 YM = Date Code Marking
 Y = Year ex: C = 2015
 M = Month ex: 9 = September

Date Code Key

Year	2015	2016	2017	2018	2019	2020	2021	2022
Code	C	D	E	F	G	H	I	J

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	71	V
Forward Continuous Current (Note 6)	I _{FM}	250	mA
Average Rectified Output Current (Note 6)	I _O	125	mA
Repetitive Peak Forward Current	I _{FRM}	450	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	4	A
		1	
		0.5	

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	350	mW
Thermal Resistance, Junction to Ambient Air (Note 6)	R _{θJA}	357	°C/W
Thermal Resistance, Junction to Solder Point	R _{θJSP}	255	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-65 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	100	—	V	I _R = 20μA
Forward Voltage	V _F	—	0.715	V	I _F = 1.0mA
			0.855		I _F = 10mA
			1.0		I _F = 50mA
			1.25		I _F = 150mA
Reverse Current (Note 7)	I _R	—	0.5	μA	V _R = 80V
			100	μA	V _R = 80V, T _J = +150°C
			30	μA	V _R = 25V, T _J = +150°C
			30	nA	V _R = 25V
Total Capacitance	C _T	—	1.5	pF	V _R = 0, f = 1.0MHz
Reverse Recovery Time	t _{RR}	—	4.0	ns	I _F = I _R = 10mA, I _{RR} = 0.1 × I _R , R _L = 100Ω
Forward Recovery Voltage	V _{FR}	—	1.75	V	I _F = 10mA, t _R = 20ns

Notes: 6. Part mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.
7. Short duration pulse test used to minimize self-heating effect.

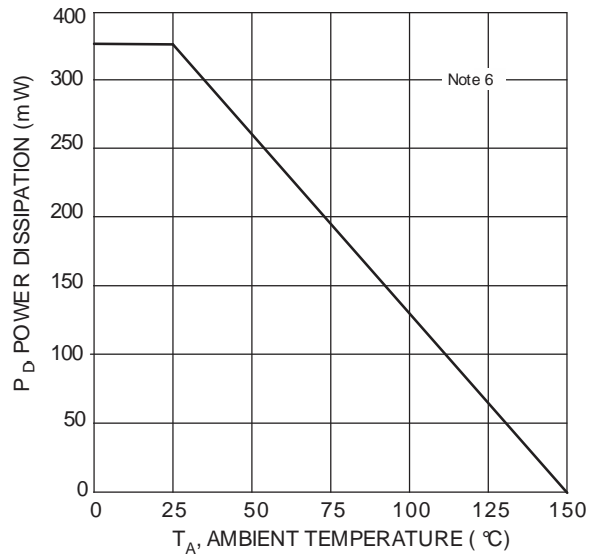


Figure 1 Power Derating Curve, Total Package

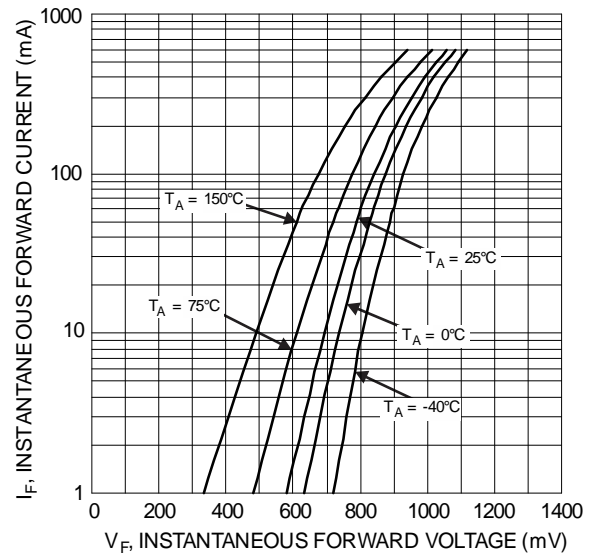


Figure 2 Typical Forward Characteristics, Per Element

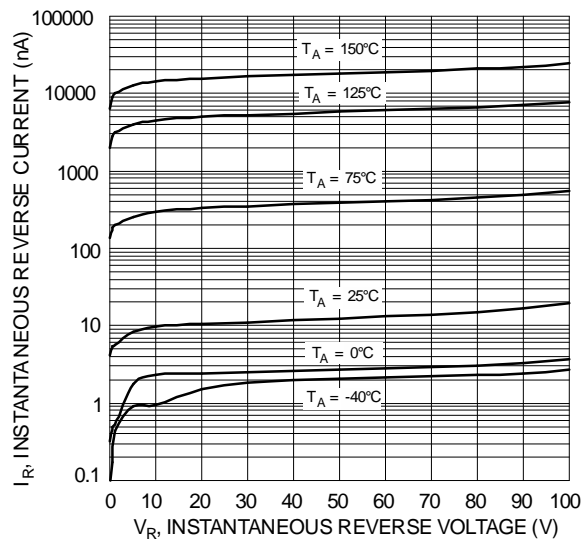


Figure 3 Typical Reverse Characteristics, Per Element

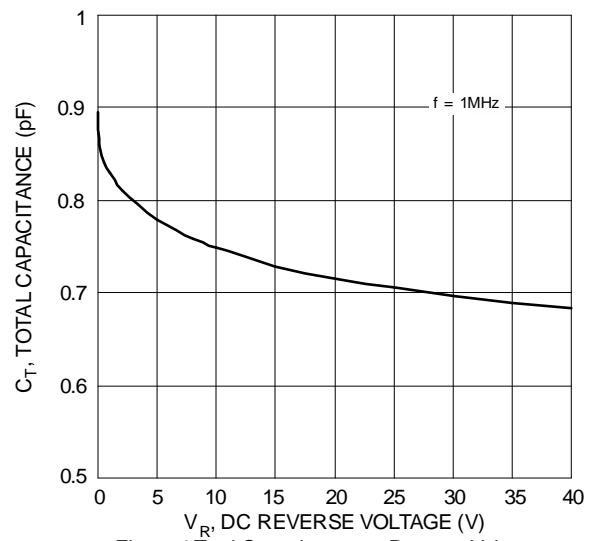
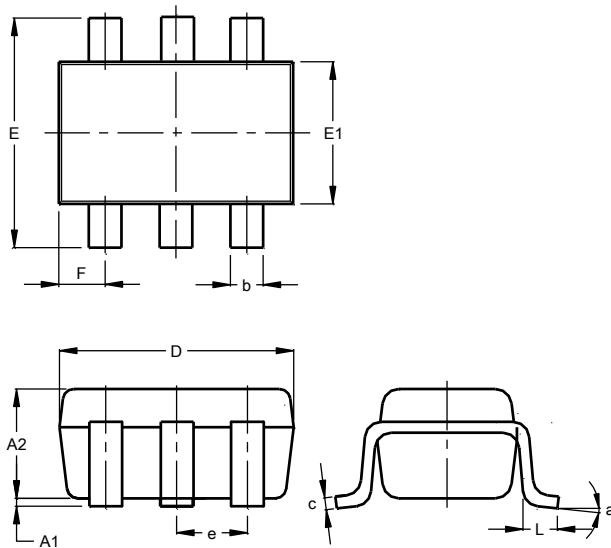


Figure 4 Total Capacitance vs. Reverse Voltage, Per Element

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

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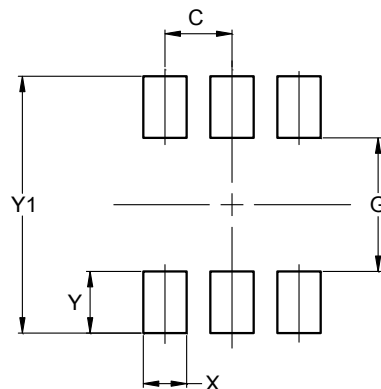


SOT363			
Dim	Min	Max	Typ
A1	0.00	0.10	0.05
A2	0.90	1.00	1.00
b	0.10	0.30	0.25
c	0.10	0.22	0.11
D	1.80	2.20	2.15
E	2.00	2.20	2.10
E1	1.15	1.35	1.30
e	0.650 BSC		
F	0.40	0.45	0.425
L	0.25	0.40	0.30
a	0°	8°	--
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT363



Dimensions	Value (in mm)
C	0.650
G	1.300
X	0.420
Y	0.600
Y1	2.500

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